

14-STAGE RIPPLE-CARRY BINARY COUNTER/DIVIDER AND OSCILLATOR

The HEF4060B is a 14-stage ripple-carry binary counter/divider and oscillator with three oscillator terminals (RS, R_{TC} and C_{TC}), ten buffered outputs (O_3 to O_9 and O_{11} to O_{13}) and an overriding asynchronous master reset input (MR). The oscillator configuration allows design of either RC or crystal oscillator circuits. The oscillator may be replaced by an external clock signal at input RS. The counter advances on the negative-going transition of RS. A HIGH level on MR resets the counter (O_3 to O_9 and O_{11} to O_{13} = LOW), independent of other input conditions.

Schmitt-trigger action in the clock input makes the circuit highly tolerant to slower clock rise and fall times.

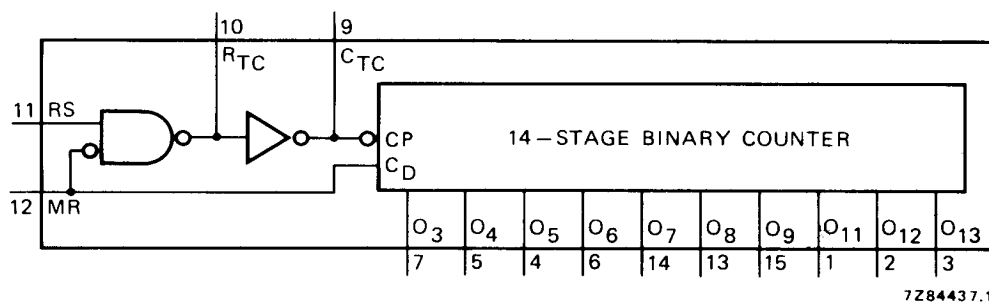
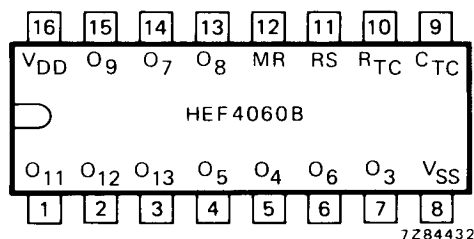


Fig. 1 Functional diagram.



PINNING

MR	master reset
RS	clock input/oscillator pin
R_{TC}	oscillator pin
C_{TC}	external capacitor connection
O_3 to O_9	} counter outputs
O_{11} to O_{13}	

Fig. 2 Pinning diagram.

HEF4060BP : 16-lead DIL; plastic (SOT-38Z).

HEF4060BD : 16-lead DIL; ceramic (cerdip) (SOT-74).

HEF4060BT : 16-lead mini-pack; plastic (SO-16; SOT-109A).

FAMILY DATA

I_{DD} LIMITS category MSI

see Family Specifications



Fig. 3 Logic diagram.

A.C. CHARACTERISTICS
 $V_{SS} = 0\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$; $C_L = 50\text{ pF}$; input transition times $\leq 20\text{ ns}$

	V_{DD} V	symbol	min.	typ.	max.	typical extrapolation formula
Propagation delays						
RS $\rightarrow$ O ₃	5			210	420 ns	183 ns + (0,55 ns/pF) C _L
HIGH to LOW	10	t _{PHL}		80	160 ns	69 ns + (0,23 ns/pF) C _L
	15			50	100 ns	42 ns + (0,16 ns/pF) C _L
LOW to HIGH	5			210	420 ns	183 ns + (0,55 ns/pF) C _L
	10	t _{PLH}		80	160 ns	69 ns + (0,23 ns/pF) C _L
	15			50	100 ns	42 ns + (0,16 ns/pF) C _L
O _n $\rightarrow$ O _{n+1}	5			25	50 ns	
HIGH to LOW	10	t _{PHL}		10	20 ns	
	15			6	12 ns	
LOW to HIGH	5			25	50 ns	
	10	t _{PLH}		10	20 ns	
	15			6	12 ns	
MR $\rightarrow$ O _n	5			100	200 ns	73 ns + (0,55 ns/pF) C _L
HIGH to LOW	10	t _{PHL}		40	80 ns	29 ns + (0,23 ns/pF) C _L
	15			30	60 ns	22 ns + (0,16 ns/pF) C _L
Output transition times	5			60	120 ns	10 ns + (1,0 ns/pF) C _L
HIGH to LOW	10	t _{THL}		30	60 ns	9 ns + (0,42 ns/pF) C _L
	15			20	40 ns	6 ns + (0,28 ns/pF) C _L
LOW to HIGH	5			60	120 ns	10 ns + (1,0 ns/pF) C _L
	10	t _{TLH}		30	60 ns	9 ns + (0,42 ns/pF) C _L
	15			20	40 ns	6 ns + (0,28 ns/pF) C _L
Minimum clock pulse width input RS	5		120	60	ns	
HIGH	10	t _{WRSH}	50	25	ns	
	15		30	15	ns	
Minimum MR pulse width; HIGH	5		50	25	ns	
	10	t _{WMRH}	30	15	ns	
	15		20	10	ns	
Recovery time for MR	5		160	80	ns	
	10	t _{RMH}	80	40	ns	
	15		60	30	ns	
Maximum clock pulse frequency input RS	5		4	8	MHz	
	10	f _{max}	10	20	MHz	
	15		15	30	MHz	

A.C. CHARACTERISTICS

$V_{SS} = 0\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$; input transition times $\leq 20\text{ ns}$

	V_{DD} V	typical formula for P (μW)*
Dynamic power dissipation per package (P)	5	$700 f_i + f_o C_L V_{DD}^2$
	10	$3\,300 f_i + f_o C_L V_{DD}^2$
	15	$8\,900 f_i + f_o C_L V_{DD}^2$
Total power dissipation when using the on-chip oscillator (P)	5	$700 f_{osc} + f_o C_L V_{DD}^2 + 2C_t V_{DD}^2 f_{osc} + 690 V_{DD}$
	10	$3\,300 f_{osc} + f_o C_L V_{DD}^2 + 2C_t V_{DD}^2 f_{osc} + 6\,900 V_{DD}$
	15	$8\,900 f_{osc} + f_o C_L V_{DD}^2 + 2C_t V_{DD}^2 f_{osc} + 22\,000 V_{DD}$

* where:

f_i = input frequency (MHz)

f_o = output frequency (MHz)

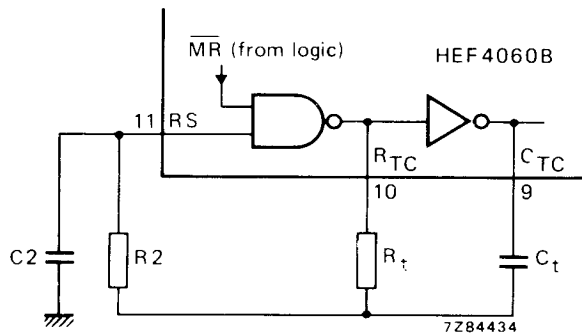
C_L = load capacitance (pF)

V_{DD} = supply voltage (V)

C_t = timing capacitance (pF)

f_{osc} = oscillator frequency (MHz)

RC oscillator



Typical formula for oscillator frequency:

$$f_{osc} = \frac{1}{2,3 \times R_T \times C_T}$$

Fig. 4 External component connection for RC oscillator.

Timing component limitations

The oscillator frequency is mainly determined by $R_T C_T$, provided $R_T \ll R_2$ and $R_2 C_2 \ll R_T C_T$. The function of R_2 is to minimize the influence of the forward voltage across the input protection diodes on the frequency. The stray capacitance C_2 should be kept as small as possible. In consideration of accuracy, C_T must be larger than the inherent stray capacitance. R_T must be larger than the LOCMOS 'ON' resistance in series with it, which typically is 500Ω at $V_{DD} = 5 \text{ V}$, 300Ω at $V_{DD} = 10 \text{ V}$ and 200Ω at $V_{DD} = 15 \text{ V}$.

The recommended values for these components to maintain agreement with the typical oscillation formula are:

$$C_T \geq 100 \text{ pF, up to any practical value,}$$

$$10 \text{ k}\Omega \leq R_T \leq 1 \text{ M}\Omega.$$

Typical crystal oscillator circuit

In Fig. 5, R_2 is the power limiting resistor. For starting and maintaining oscillation a minimum transconductance is necessary.

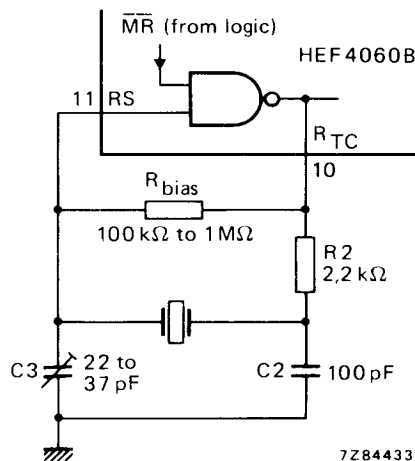


Fig. 5 External component connection for crystal oscillator.

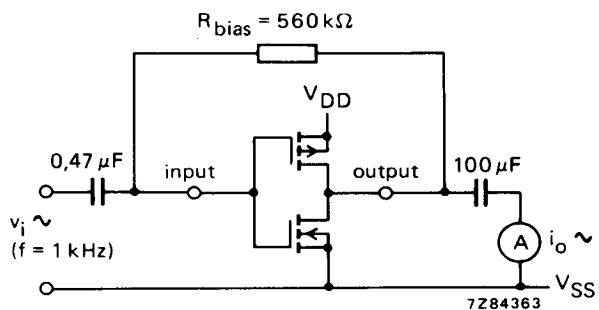
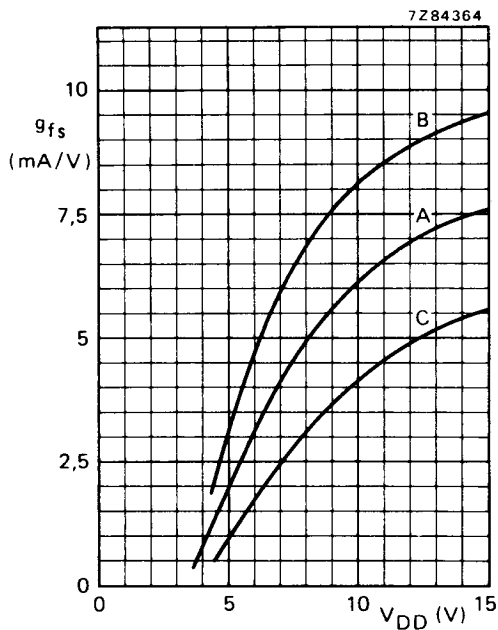


Fig. 6 Test set-up for measuring forward transconductance $g_{fs} = di_o/dv_i$ at v_o is constant (see also graph Fig. 7); MR = LOW.



Curves in Fig. 7:

A: average

B: average + 2 s,

C: average - 2 s, in where:
's' is the observed standard deviation.

Fig. 7 Typical forward transconductance g_{fs} as a function of the supply voltage at $T_{amb} = 25\text{ }^{\circ}\text{C}$.

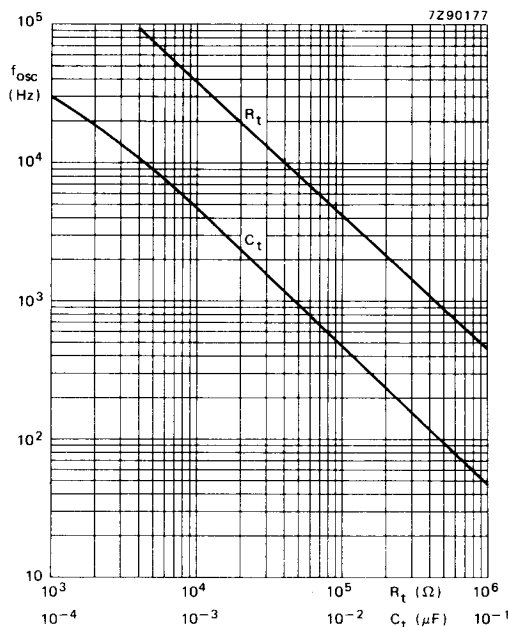


Fig. 8 RC oscillator frequency as a function of R_t and C_t at $V_{DD} = 5$ to 15 V; $T_{amb} = 25$ °C.
 C_t curve at $R_t = 100$ k Ω ; $R_2 = 470$ k Ω .
 R_t curve at $C_t = 1$ nF; $R_2 = 5 R_t$.

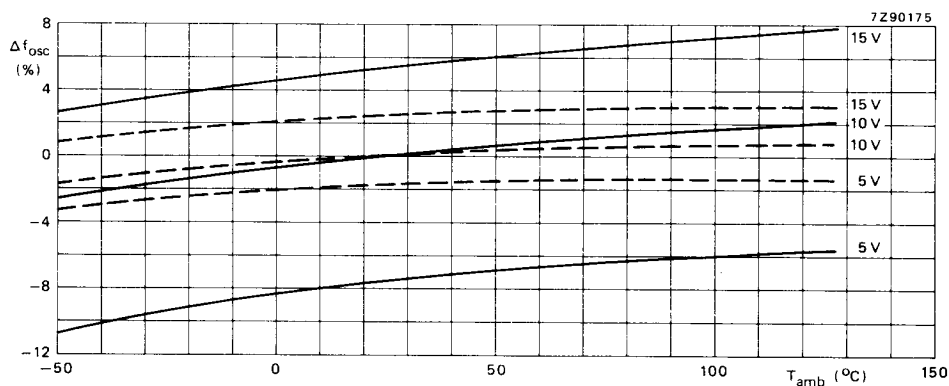


Fig. 9 Oscillator frequency deviation (Δf_{osc}) as a function of ambient temperature; referenced at: f_{osc} at $T_{amb} = 25$ °C and $V_{DD} = 10$ V.

— $R_t = 100$ k Ω ; $C_t = 1$ nF; $R_2 = 0$.
 - - - $R_t = 100$ k Ω ; $C_t = 1$ nF; $R_2 = 300$ k Ω .